

All nets ending in _P or _N are differential pairs;
from what I can tell, the H⁺ stuff is meant for
higher-speed; the L⁺ stuff can be used differentially
or single-ended. I have routed everything differentially,
so, for single-ended use, you would tie the _N line to GND.

I managed to balance all of the differential pairs
to 3.3" (3300mil) to a tolerance of 25mil
so you can run your busses however you need
to without the adapter adding time skew.
This tolerance is based on the DDR2 spec.

Bypass capacitors at ingress and
egress of each power rail. Probably
overkill, but my thought is to avoid
coupling in noise from the environment,
bugs in the board, or between the devices.

The +3v3 rail is present on both EXT connectors and
the FMC connector. I have tied them all together and added
bypass capacitance in strategic places.

Values are nominal; board sized for 0805 SMD.
3v3 bypass at: EXT1/EXT2 termination,
FMC termination, and off-board connection.

2v5 bypass at EXT1/EXT2 termination

Remaining, non-differential IOs on the EXT sockets
are brought out to 0.1" pin headers for use as **GPIOs**.
I couldn't find any more useful pins on the FMC that Xilinx
typically ties into... and I'm not sure I can get much more on
board without adding another layer.

Although they are not specifically rated for differential
use, I routed the GPIOs differentially based on the adjacent
pins on the EXT2 connectors and with ground guards at
the 0.1" connectors.

Connections between EXT1 and EXT2 QST connectors and FMC connector.
Also present are two 100mil headers bringing out the remaining
GPIOs from the EXT connectors.

TITLE: 20150104_QSE_to_FMC_6Layer_R3.1

Document Number:

REV:

Date: 1/4/2015 7:42:13 PM

Sheet: 1/2



TITLE: 20150104_QSE_to_FMC_6Layer_R3.1

REV:

Sheet: 2/2



